# An Ultra-small 1.6 mm<sup>2</sup>, 17 mΩ, 2.5 A, 125°C-Rated Internally-protected Integrated Power Switch with Discharge

### **General Description**

The SLG59M1658V is a high performance 17 m $\Omega$ , 2.5 A single-channel nFET integrated power switch which can operate with a 2.5 V to 5.5 V V<sub>DD</sub> supply to switch power rails from as low as 0.9 V up to the supply voltage. The SLG59M1658V incorporates two-level overload current protection, thermal shutdown protection, fast output voltage discharge, and in-rush current control which can easily be adjusted by a small external capacitor.

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Using a proprietary MOSFET design, the SLG59M1658V achieves a stable 17 m $\Omega$  RDS<sub>ON</sub> across a wide input voltage range. In addition, the SLG59M1658V's package also exhibits low thermal resistance for high-current operation using Silego's proprietary CuFET technology.

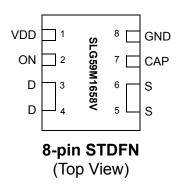
Fully specified over the -40 °C to 125 °C temperature range, the SLG59M1658V is packaged in a space-efficient, low thermal resistance, RoHS-compliant 1.0 mm x 1.6 mm STDFN package.

### Features

- 1.0 x 1.6 x 0.55 mm STDFN 8L package (2 fused pins for drain and 2 fused pins for source)
- Logic level ON pin capable of supporting 0.85 V CMOS Logic
- · User selectable ramp rate with external capacitor
- 17 m $\Omega$  RDS<sub>ON</sub> while supporting 2.5 A
- · Discharges load when off
- Two Over Current Protection Modes
- Short Circuit Current Limit
- Active Current Limit
- Over Temperature Protection
- Pb-Free / Halogen-Free / RoHS compliant
- Operating Temperature: -40 °C to 125°C
- Operating Voltage: 2.5 V to 5.5 V

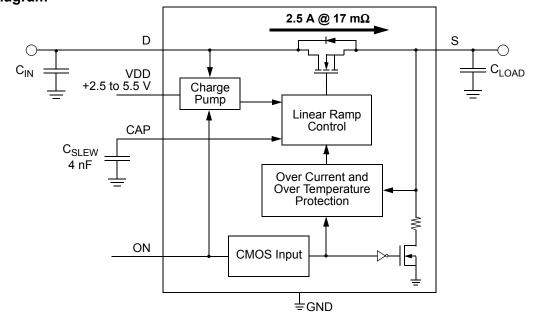
### Block Diagram

### **Pin Configuration**



#### Applications

- Notebook Power Rail Switching
- Tablet Power Rail Switching
- Smartphone Power Rail Switching





### **Pin Description**

Pin #	Pin Name	Туре	Pin Description
1	VDD	PWR	With an internal 1.8 V UVLO threshold, VDD supplies the power for the operation of the power switch and internal control circuitry. Bypass the VDD pin to GND with a 0.1 $\mu$ F (or larger) capacitor.
2	ON	Input	A low-to-high transition on this pin initiates the operation of the SLG59M1658V's state machine. ON is a CMOS input with V <sub>IL</sub> < 0.25 V and V <sub>IH</sub> > 0.85 V thresholds. While there is an internal pull-down circuit to GND (~4 MΩ), connect this pin directly to a general-purpose output (GPO) of a microcontroller, an application processor, or a system controller. Do not allow this pin to be open-circuited.
3, 4	D	MOSFET	Drain terminal connection of the n-channel MOSFET (2 pins fused for V <sub>D</sub> ). Connect at least a low-ESR 0.1 $\mu$ F capacitor from this pin to ground. Capacitors used at V <sub>D</sub> should be rated at 10 V or higher.
5, 6	S	MOSFET	Source terminal connection of the n-channel MOSFET (2 pins fused for V <sub>S</sub> ). Connect a low-ESR capacitor from this pin to ground and consult the Electrical Characteristics table for recommended C <sub>LOAD</sub> range. Capacitors used at V <sub>S</sub> should be rated at 10 V or higher.
7	САР	Input	A low-ESR, stable dielectric, ceramic surface-mount capacitor connected from CAP pin to GND sets the V <sub>S</sub> slew rate and overall turn-on time of the SLG59M1658V. For best performance C <sub>SLEW</sub> value should be $\geq$ 1.5 nF and voltage level should be rated at 10 V or higher.
8	GND	GND	Ground connection. Connect this pin to system analog or power ground plane.

### **Ordering Information**

Part Number	Туре	Production Flow
SLG59M1658V	STDFN 8L	Extended Industrial, -40 °C to 125 °C
SLG59M1658VTR	STDFN 8L (Tape and Reel)	Extended Industrial, -40 °C to 125 °C



### **Absolute Maximum Ratings**

Parameter	Description	Conditions	Min.	Тур.	Max.	Unit
V <sub>DD</sub>	Power Supply				7	V
V <sub>D</sub> to GND	Power Switch Input Voltage to GND		-0.3		7	V
V <sub>S</sub> to GND	Power Switch Output Voltage to GND		-0.3		V <sub>D</sub>	V
ON and CAP to GND	ON and CAP Pin Voltages to GND		-0.3		7	V
Τ <sub>S</sub>	Storage Temperature		-65		150	°C
ESD <sub>HBM</sub>	ESD Protection	Human Body Model	2000			V
ESD <sub>CDM</sub>	ESD Protection	Charged Device Model	1000			V
MSL	Moisture Sensitivity Level				1	L
$\theta_{JA}$	Thermal Resistance	1.0 x 1.6 mm, 8L STDFN; Determined us- ing 1 in <sup>2</sup> , 1 oz. copper pads under each VD and VS terminals and FR4 pcb material		74		°C/W
W <sub>DIS</sub>	Package Power Dissipation				0.4	W
MOSFET IDS	Max Continuous Switch Current				2.5	Α
MOSFET IDS <sub>PK</sub>	Peak Current from Drain to Source	For no more than 1 ms with 1% duty cycle			3.5	Α
Note: Stresses gre	eater than those listed under "Absolute N	Maximum Ratings" may cause permanent damage se or any other conditions above those indicate				

specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

### **Electrical Characteristics**

 $T_A$  = -40 to 125 °C (unless otherwise stated)

Parameter	Description	Conditions	Min.	Тур.	Max.	Unit
V <sub>DD</sub>	Power Supply Voltage	-40 to 125°C	2.5		5.5	V
V <sub>DD_UVLO</sub>	V <sub>DD</sub> Undervoltage Lockout Threshold	V <sub>DD</sub> ↑		1.8		V
		when OFF; $T_A = 70 \text{ °C};$ V <sub>S</sub> = 0 V; V <sub>D</sub> = V <sub>DD</sub> = 5.5 V			1	μA
I <sub>DD</sub>	Power Supply Current (PIN 1)	when OFF; $T_A$ = 85 °C; V <sub>S</sub> = 0 V; V <sub>D</sub> = V <sub>DD</sub> = 5.5 V			1	μA
		when OFF; $T_A = 125 \text{ °C};$ V <sub>S</sub> = 0 V; V <sub>D</sub> = V <sub>DD</sub> = 5.5 V			1	μA
		when ON, no Load		75	100	μA
		T <sub>A</sub> 25°C @ 100 mA		17	20.4	mΩ
RDS <sub>ON</sub>	Static Drain to Source ON Resistance	T <sub>A</sub> 85°C @ 100 mA		20.5	24	mΩ
		T <sub>A</sub> 125°C @ 100 mA		24	28.8	mΩ
VD	Drain Voltage		0.9		V <sub>DD</sub>	V
		V <sub>D</sub> = V <sub>DD</sub> = 5.5 V; V <sub>S</sub> = 0 V; ON = 0 V; T <sub>A</sub> = 70°C			1	μA
I <sub>FET_OFF</sub>	MOSFET OFF Leakage Current	V <sub>D</sub> = V <sub>DD</sub> = 5.5 V; V <sub>S</sub> = 0 V; ON = 0 V; T <sub>A</sub> = 85°C			1	μA
		V <sub>D</sub> = V <sub>DD</sub> = 5.5 V; V <sub>S</sub> = 0 V; ON = 0 V; T <sub>A</sub> = 125°C			5	μA



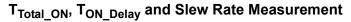
### Electrical Characteristics (continued)

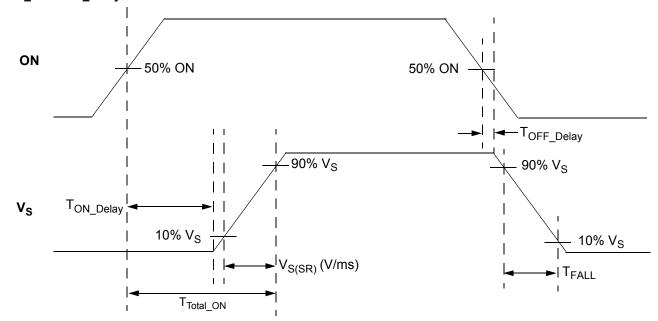
 $T_A = -40$  to 125 °C (unless otherwise stated)

Parameter	Description	Conditions	Min.	Тур.	Max.	Unit
T <sub>ON_Delay</sub>	ON pin Delay Time	50% ON to Ramp Begin		200		μs
		10% $V_{\rm S}$ to 90% $V_{\rm S}$	Сс	Configurable <sup>1</sup>		
V <sub>S(SR)</sub> Slew Rate		Example: $C_{SLEW}$ (PIN 7) = 4 nF, $V_{DD}$ = $V_{D}$ = 5 V, $C_{LOAD}$ = 10 $\mu$ F, $R_{LOAD}$ = 20 $\Omega$		3.3		V/ms
		50% ON to 90% V <sub>S</sub>	Co	onfigurable	e <sup>1</sup>	ms
T <sub>Total_ON</sub> Total Turn On Time		Example: $C_{SLEW}$ (PIN 7) = 4 nF, $V_{DD}$ = $V_D$ = 5 V, $C_{LOAD}$ = 10 $\mu$ F, $R_{LOAD}$ = 20 $\Omega$		1.50		ms
T <sub>OFF_Delay</sub>	OFF Delay Time	50% ON to V <sub>S</sub> Fall Start, V <sub>DD</sub> = V <sub>D</sub> = 5 V, no C <sub>LOAD</sub> , R <sub>LOAD</sub> = 20 Ω		8		μs
T <sub>FALL</sub>	V <sub>S</sub> Fall Time	90% V <sub>S</sub> to 10% V <sub>S</sub> , V <sub>DD</sub> = V <sub>D</sub> = 5 V, no C <sub>LOAD</sub> , R <sub>LOAD</sub> = 20 $\Omega$		3.3		μs
C <sub>LOAD</sub>	Output Load Capacitance	$\rm C_{LOAD}$ connected from $\rm V_S$ to GND			500	μF
R <sub>DIS</sub>	Discharge Resistance		100	200	300	Ω
ON_V <sub>IH</sub>	High Input Voltage on ON pin		0.85		$V_{DD}$	V
$ON_V_{IL}$	Low Input Voltage on ON pin		-0.3	0	0.25	V
I	Active Current Limit (I <sub>ACL</sub> )	MOSFET will automatically limit current when $V_S > 250 \text{ mV}$		4.5		Α
I <sub>LIMIT</sub>	Short Circuit Current Limit (I <sub>SCL</sub> )	MOSFET will automatically limit current when $V_S$ < 250 mV		0.5		A
THERMON	Thermal shutoff turn-on temperature			150		°C
THERMOFF	Thermal shutoff turn-off temperature			130		°C
THERM	Thermal shutoff time				1	ms



SLG59M1658V



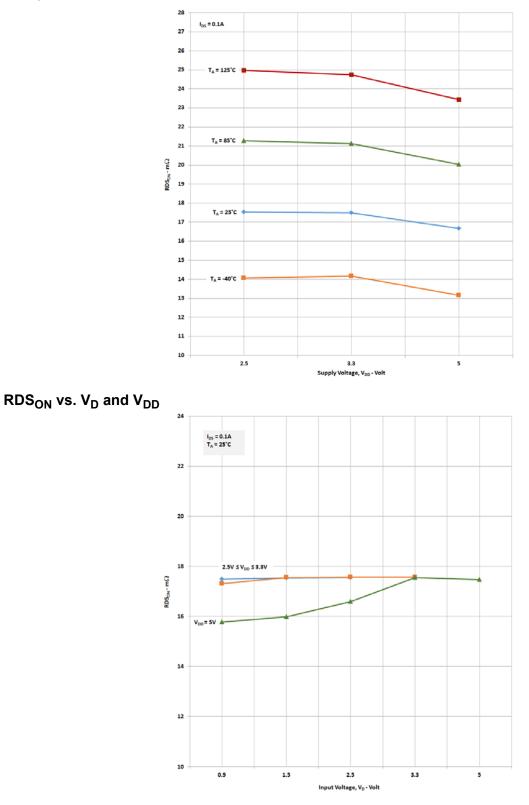


Note: Rise and Fall times of the ON signal are 100 ns

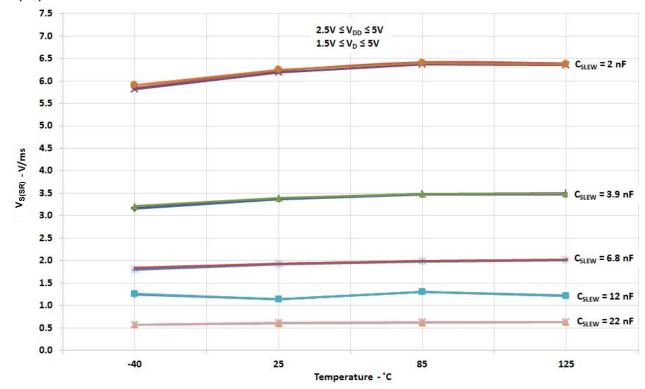


### **Typical Performance Characteristics**

### RDS<sub>ON</sub> vs. V<sub>DD</sub>, and Temperature

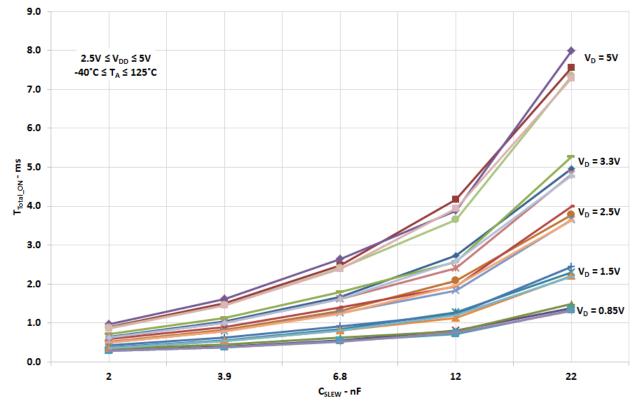






 $V_{S(SR)}$  vs. Temperature,  $V_D$ ,  $V_{DD}$ , and  $C_{SLEW}$ 

 $T_{Total\ ON}$  vs.  $C_{SLEW}\!,\,V_D\!,\,V_{DD}\!,$  and Temperature





### Typical Operation Waveforms



Figure 1. Typical Turn ON operation waveform for V<sub>DD</sub> = V<sub>D</sub> = 5 V, C<sub>SLEW</sub> = 4 nF, C<sub>LOAD</sub> = 10  $\mu$ F, R<sub>LOAD</sub> = 20  $\Omega$ 



Figure 2. Typical Turn ON operation waveform for V<sub>DD</sub> = V<sub>D</sub> = 5 V, C<sub>SLEW</sub> = 12 nF, C<sub>LOAD</sub> = 10  $\mu$ F, R<sub>LOAD</sub> = 20  $\Omega$ 



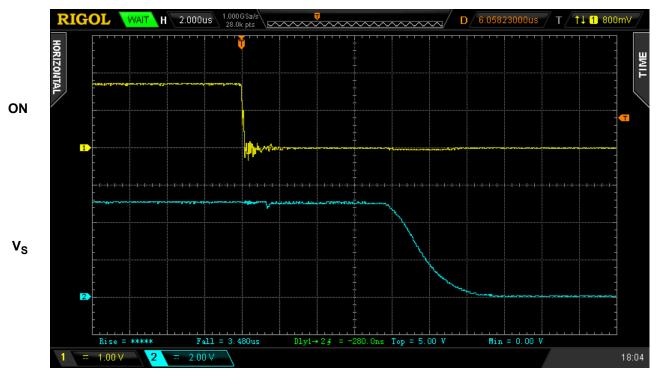


Figure 3. Typical Turn OFF operation waveform for V<sub>DD</sub> = V<sub>D</sub> = 5 V, C<sub>SLEW</sub> = 4 nF, no C<sub>LOAD</sub>, R<sub>LOAD</sub> = 20  $\Omega$ 



Figure 4. Typical Turn OFF operation waveform for V<sub>DD</sub> = V<sub>D</sub> = 5 V, C<sub>SLEW</sub> = 4 nF, C<sub>LOAD</sub> = 10  $\mu$ F, R<sub>LOAD</sub> = 20  $\Omega$ 



#### SLG59M1658V Power-Up/Power-Down Sequence Considerations

To ensure glitch-free power-up under all conditions, apply V<sub>DD</sub> first, followed by V<sub>D</sub> after V<sub>DD</sub> exceeds 1 V. Then allow V<sub>D</sub> to reach 90% of its max value before toggling the ON pin from Low-to-High. Likewise, power-down in reverse order.

If  $V_{DD}$  and  $V_D$  need to be powered up simultaneously, glitching can be minimized by having a suitable load capacitor. A 10  $\mu$ F  $C_{LOAD}$  will prevent glitches for rise times of  $V_{DD}$  and  $V_D$  less than 2 ms.

If the ON pin is toggled HIGH before V<sub>DD</sub> and V<sub>D</sub> have reached their steady-state values, the IPS timing parameters may differ from datasheet specifications.

The slew rate of output V<sub>S</sub> follows a linear ramp set by a capacitor connected to the CAP pin. A larger capacitor value at the CAP pin produces a slower ramp, reducing inrush current from capacitive loads.

#### SLG59M1658V Current Limiting

The SLG59M1658V has two modes of current limiting, differentiated by the output (Source pin) voltage.

#### 1. Standard Current Limiting Mode (with Thermal Protection)

When V(S) > 250 mV, the output current is initially limited to the Active Current Limit specification given in the Electrical Characteristics table. The current limiting circuit is very fast and responds within a few micro-seconds to sudden loads. When overload is sensed, the current limiting circuit increases the FET resistance to keep the current from exceeding the Active Current Limit.

However, if an overload condition persists, the die temperature rise due to the increased FET resistance while at maximum current can activate Thermal Protection. If the die temperature exceeds the THERM<sub>ON</sub> specification, the FET is shut completely OFF, allowing the die to cool. When the die cools to the THERM<sub>OFF</sub> temperature, the FET is allowed to turn back on. This process may repeat as long as the overload condition is present.

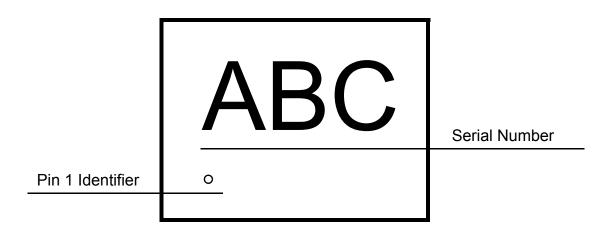
#### 2. Short Circuit Current Limiting Mode (with Thermal Protection)

When V(S) < 250 mV (which is the case with a hard short, such as a solder bridge on the power rail), the current is limited to approximately 500 mA. Thermal Protection is also present, but since the Short Circuit Current Limit is much lower than Standard Current Limit, activation may only occur at higher ambient temperatures.

For more information on Silego GreenFET3 integrated power switch features, please visit our <u>Application Notes</u> page at our website and see <u>App Note "AN-1068 GreenFET3 Integrated Power Switch Basics"</u>.



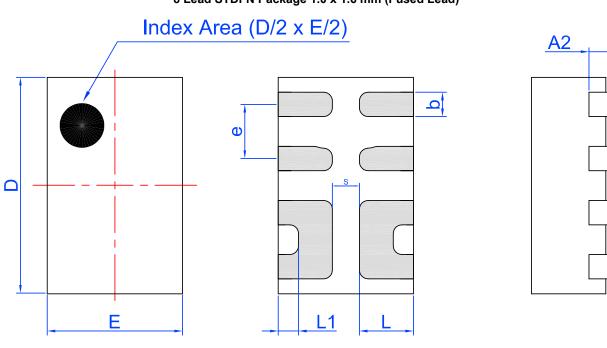
### Package Top Marking System Definition

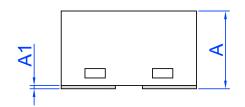


ABC - Part Serial Number Field each A, B, and C character can be A-Z and 0-9



### **Package Drawing and Dimensions**





### Unit: mm

Symbol	Min	Nom.	Max	Symbol	Min	Nom.	Max
A	0.50	0.55	0.60	D	1.55	1.60	1.65
A1	0.005	-	0.060	E	0.95	1.00	1.05
A2	0.10	0.15	0.20	L	0.35	0.40	0.45
b	0.13	0.18	0.23	L1	0.10	0.15	0.20
е	(	).40 BSC	,	S	(	0.2 REF	

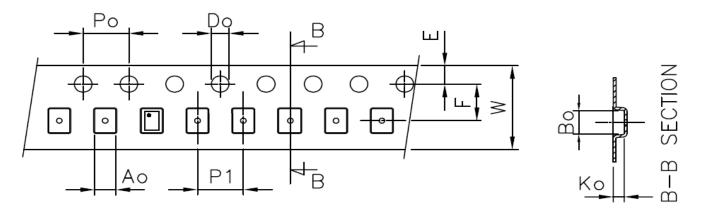


### **Tape and Reel Specifications**

Dookogo	# of	Nominal	Max	Units	Reel &	Leade	r (min)	Trailer	(min)	Таре	Part
Package Type	# of Pins	Package Size [mm]	per Reel	per Box	Hub Size [mm]	Pockets	Length [mm]	Pockets	Length [mm]	Width [mm]	Pitch [mm]
STDFN 8L 1x1.6mm 0.4P FC Green	8	1.0 x 1.6 x 0.55	3,000	3,000	178 / 60	100	400	100	400	8	4

### **Carrier Tape Drawing and Dimensions**

Package Type	PocketBTM Length	PocketBTM Width	Pocket Depth	Index Hole Pitch	Pocket Pitch	Index Hole Diameter	Index Hole to Tape Edge		Tape Width
	A0	В0	K0	P0	P1	D0	E	F	w
STDFN 8L 1x1.6mm 0.4P FC Green	1.12	1.72	0.7	4	4	1.55	1.75	3.5	8



### **Recommended Reflow Soldering Profile**

Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 0.88 mm<sup>3</sup> (nominal). More information can be found at www.jedec.org.



### **Revision History**

Date	Version	Change
2/23/2017	1.00	Production Release

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